

ABSTRACT OF THE DISCLOSURE

To provide a method and an apparatus that can execute simultaneous injection molding of a plurality of different resin components using a mold construction that makes possible simultaneous main-sub component molding, without having to make the mold and device larger. A simultaneous main-sub component molding method utilizes a mold device having a first cavity C1 for molding a first resin component and a second cavity C2 for molding a second resin component. The mold cavities C1 and C2 are provided in a pair of opposed mold halves 100, 200 which close for the molding operation and open to remove the molded parts. In this mold device, injection molding of a plurality of different types of resin components 20, 23 is simultaneous. The first resin component is configured from a large resin component that is substantially circular, U-shaped, or L-shaped. The second resin component is configured from a small resin component that can be positioned inside an open portion of the first resin component. The mold halves 100, 200, which have the smaller cavity C2 inside the larger cavity C1, are substantially the same size as a mold which has only first cavity C1, and which independently molds the first resin component. As a result, the mold is smaller than a conventional mold 4 (5) for simultaneous main-sub component molding, in which the second cavities C2 are positioned outside the first cavities C1.